SOIC8
CASE 751EG
ISSUE O

DATE 30 SEP 2016

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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98AON13741G

DOCUMENT NUMBER: 98AON13741G
DESCRIPTION: SOIC8

NOTES: UNLESS OTHERWISE SPECIFIED
A. THIS PACKAGE CONFORMS TO JEDEC MS-012 VARIATION A EXCEPT WHERE NOTED.
B. ALL DIMENSIONS ARE IN MILLIMETERS.
C. OUT OF JEDEC STANDARD VALUE.
D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
E. LAND PATTERN AS PER IPC SOIC127P600X175~8M.

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